

Data Sheet

July 2004

Features

Single 2.7-3.6 volt supply

Programmable μ–law/A-law Codec and filters

Fully differential to output driver

SSI digital interface

· Individual transmit and receive mute controls

• 0 dB gain in receive path

• 6 dB gain in transmit path

Low power operation

• ITU-T G.714 compliant

Applications

- · Cellular radio sets
- · Local area communications stations
- Line cards
- · Battery operated equipment

Ordering Information

MT91L62AE 20 Pin Plastic DIP (300 mil)

MT91L62AS 20 Pin SOIC MT91L62AN 20 Pin SSOP

-40°C to +85°C

Description

The MT91L62 3 V single rail Codec incorporates a built-in Filter/Codec, transmit anti-alias filter, a reference voltage and bias source. The device supports both A-law and μ -law requirements. The MT91L62 is a true 3 V device employing a fully differential architecture to ensure wide dynamic range.

An analog output driver is provided, capable of driving a 20 k ohm load.

The MT91L62 is fabricated in Zarlink's ISO²-CMOS technology ensuring low power consumption and high reliability.

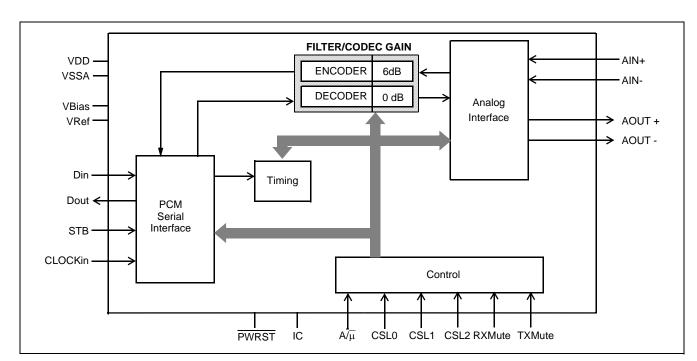


Figure 1 - Functional Block Diagram

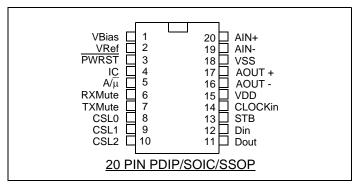


Figure 2 - Pin Connections

Pin Description

Pin#	Name	Description
1	V _{Bias}	Bias Voltage (Output). $(V_{DD}/2)$ volts is available at this pin for biasing external amplifiers. Connect 0.1 μ F capacitor to V_{SS} .
2	V_{Ref}	Reference Voltage for Codec (Output). Nominally [($V_{DD}/2$)-1.1] volts. Used internally. Connect 0.1 μ F capacitor to V_{SS} .
3	PWRST	Power-up Reset. Resets internal state of device via Schmitt Trigger input (active low).
4	IC	Internal Connection. Tie externally to V _{SS} for normal operation.
5	$A/\overline{\mu}$	$A/\overline{\mu}$ Law Selection. CMOS level compatable input pin governs the companding law used by the device. A-law selected when pin tied to V_{DD} or μ -law selected when pin tied to V_{SS} .
6	RXMute	Receive Mute. When 1, the transmit PCM is forced to negative zero code. When 0, normal operation. CMOS level compatable input.
7	TXMute	Transmit Mute. When 1, the transmit PCM is forced to negative zero code. When 0, normal operation. CMOS level compatable input.
8 9 10	CSL0 CSL1 CSL2	Clock Speed Select. These pins are used to program the speed of the SSI mode as well as the conversion rate between the externally supplied MCL clock and the 512 KHz clock required by a filter/codec. Refer to Table 2 for details. CMOS level compatable input.
11	D _{out}	Data Output. A tri-state digital output for 8-bit wide channel data being sent to the Layer 1 device. Data is shifted out via the pin concurrent with the rising edge of BCL during the timeslot defined by STB.
12	D _{in}	Data Input. A digital input for 8-bit wide data from the layer 1 device. Data is sampled on the falling edge of BCL during the timeslot defined by STB. CMOS level compatable input.
13	STB	Data Strobe. This input determines the 8-bit timeslot used by the device for both transmit and receive data. This active high signal has a repetition rate of 8 kHz. CMOS level compatable input.
14	CLOCKin	Clock (Input). The clock provided to this input pin is used by the internal device functions. Connect bit clock to this pin when it is 512 kHz or greater. Connect a 4096 kHz clock to this pin when the bit clock is 128 kHz or 256 kHz. CMOS level compatable input.
15	V _{DD}	Positive Power Supply. Nominally 3 volts.
16	AOUT-	Inverting Analog Output. (balanced).
17	AOUT+	Non-Inverting Analog Output. (balanced).
18	V_{SS}	Ground. Nominally 0 volts.

Pin Description (continued)

Pin#	Name	Description
19	Ain-	Inverting Analog Input. No external anti-aliasing is required.
20	Ain+	Non-Inverting Analog Input. Non-inverting input. No external anti-aliasing is required.

Overview

The 3 V Single-Rail Codec features complete Analog/Digital and Digital/Analog conversion of audio signals (Filter/Codec) and an analog interface to a standard analog transmitter and receiver (analog Interface). The receiver amplifier is capable of driving a 20 k ohm load.

Functional Description

Filter/Codec

The Filter/Codec block implements conversion of the analog 0-3.3 kHz speech signals to/from the digital domain compatible with 64 kb/s PCM B-Channels. Selection of companding curves and digital code assignment are programmable. These are ITU-T G.711 A-law or μ -Law, with true-sign/Alternate Digit Inversion.

The Filter/Codec block also implements a transmit audio path gain in the analog domain. Figure 3 depicts the nominal half-channel for the MT91L62.

The internal architecture is fully differential to provide the best possible noise rejection as well as to allow a wide dynamic range from a single 3 volt supply design. This fully differential architecture is continued into the Analog Interface section to provide full chip realization of these capabilities for the external functions.

A reference voltage (V_{Ref}), for the conversion requirements of the Codec section, and a bias voltage (V_{Bias}), for biasing the internal analog sections, are both generated on-chip. V_{Bias} is also brought to an external pin so that it may be used for biasing external gain setting amplifiers. A 0.1 μ F capacitor must be connected from V_{Bias} to analog ground at all times. Likewise, although V_{Ref} may only be used internally, a 0.1 μ F capacitor from the V_{Ref} pin to ground is required at all times. The analog ground reference point for these two capacitors must be physically the same point. To facilitate this the V_{Ref} and V_{Bias} pins are situated on adjacent pins.

The transmit filter is designed to meet ITU-T G.714 specifications. An anti-aliasing filter is included. This is a second order lowpass implementation with a corner frequency at 25 kHz.

The receive filter is designed to meet ITU-T G.714 specifications. Filter response is peaked to compensate for the sinx/x attenuation caused by the 8 kHz sampling rate.

Companding law selection for the Filter/Codec is provided by the $A/\overline{\mu}$ companding control pin. Table 1 illustrates these choices.

Code	ITU-T (G.711)							
Coue	μ -Law	A-Law						
+ Full Scale	1000 0000	1010 1010						
+ Zero	1111 1111	1101 0101						
-Zero (quiet code)	0111 1111	0101 0101						
- Full Scale	0000 0000	0010 1010						

Table 1 - Law Selection

Analog Interfaces

Standard interfaces are provided by the MT91L62. These are:

- The analog inputs (transmitter), pins AIN+/AIN-. The maximum peak to peak input is 2.123 Vpp μ-law across AIN+/AIN- and 2.2 Vpp A-law across these pins.
- The analog outputs (receiver), pins AOUT+/AOUT-. This internally compensated fully differential output driver is capable of driving a load of 20 k ohms.

PCM Serial Interface

A serial link is required to transport data between the MT91L62 and an external digital transmission device. The MT91L62 utilizes the strobed data interface found on many standard Codec devices. This interface is commonly referred to as Simple Serial Interface (SSI).

The bit clock rate is selected by setting the CSL2-0 control pins as shown in Figure 2.

Quiet Code

The PCM serial port can be made to send quiet code to the decoder and receive filter path by setting the RxMute pin high. Likewise, the PCM serial port will send quiet code in the transmit path when the TxMute pin is high. When either of these pins are low their respective paths function normally. The -Zero entry of Table 1 is used for the quiet code definition.

CSL ₂	CSL ₁	CSL ₀	External Clock Bit Rate (kHz)	CLOCKin (kHz)
1	0	0	128	4096
1	0	1	256	4096
0	0	0	512	512
0	0	1	1536	1536
0	1	0	2048	2048
0	1	1	4096	4096

Table 2 - Bit Clock Rate Selection

SSI Mode

The SSI BUS consists of input and output serial data streams named Din and Dout respectively, a Clock input signal (CLOCKin), and a framing strobe input (STB). A 4.096 MHz master clock is also required for SSI operation if the bit clock is less than 512 kHz. The timing requirements for SSI are shown in Figures 5 & 6.

In SSI mode the MT91L62 supports only B-Channel operation. Hence, in SSI mode transmit and receive B-Channel data are always in the channel defined by the STB input.

The data strobe input STB determines the 8-bit timeslot used by the device for both transmit and receive data. This is an active high signal with an 8 kHz repetition rate.

SSI operation is separated into two categories based upon the data rate of the available bit clock. If the bit clock is 512 kHz or greater then it is used directly by the internal MT91L62 functions allowing synchronous operation. If the available bit clock is 128 kHz or 256 kHz, then a 4096 kHz master clock is required to derive clocks for the internal MT91L62 functions.

Applications where Bit Clock (BCL) is below 512 kHz are designated as asynchronous. The MT91L62 will re-align its internal clocks to allow operation when the external master and bit clocks are asynchronous. Control pins CSL2, CSL1 and CSL0 are used to program the bit rates.

For synchronous operation, data is sampled from Din, on the falling edge of BCL during the time slot defined by the STB input. Data is made available, on Dout, on the rising edge of BCL during the time slot defined by the STB input. Dout is tri-stated at all times when STB is not true. If STB is valid, then quiet code will be transmitted on Dout during the valid strobe period. There is no frame delay through the PCM serial circuit for synchronous operation.

For asynchronous operation Dout and Din are as defined for synchronous operation except that the allowed output jitter on Dout is larger. This is due to the resynchronization circuitry activity and will not affect operation since the bit cell period at 128 kb/s and 256 kb/s is relatively large. There is a one frame delay through the PCM serial circuit for asynchronous operation. Refer to the specifications of Figures 5 & 6 for both synchronous and asynchronous SSI timing.

PWRST

While the MT91L62 is held in PWRST no device control or functionality is possible.

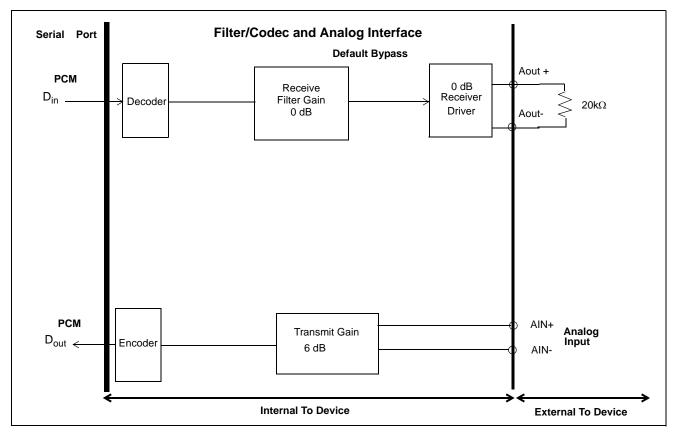


Figure 3 - Audio Gain Partitioning

Applications

Figure 4 shows an application of the MT91L62 in a line card.

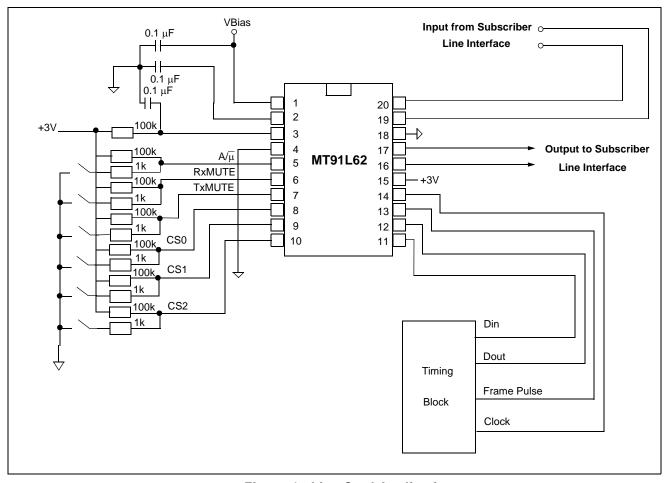


Figure 4 - Line Card Application

Absolute Maximum Ratings[†]

	Parameter	Symbol	Min.	Max.	Units
1	Supply Voltage	V _{DD} - V _{SS}	- 0.3	5	V
2	Voltage on any I/O pin	V _I /V _O	V _{SS} - 0.3	V _{DD} + 0.3	٧
3	Current on any I/O pin (transducers excluded)	I _I /I _O		± 20	mA
4	Storage Temperature	T _S	- 65	+ 150	°C
5	Power Dissipation (package)	P_{D}		750	mW

Exceeding these values may cause permanent damage. Functional operation under these conditions is not implied.

$\textbf{Recommended Operating Conditions} \ - \ \ \text{Voltages are with respect to V}_{SS} \ \text{unless otherwise stated}.$

	Characteristics	Sym.	Min.	Тур.	Max.	Units	Test Conditions
1	Supply Voltage	V_{DD}	2.7	3	3.6	V	
2	CMOS Input Voltage (high)	V _{IHC}	0.9*V _{DD}		V_{DD}	V	
3	CMOS Input Voltage (low)	V _{ILC}	V _{SS}		0.1*V _{DD}	V	
4	Operating Temperature	T _A	- 40		+ 85	°C	

Power Characteristics

	Characteristics	Sym.	Min.	Тур.	Max.	Units	Test Conditions
1	Static Supply Current (clock disabled)	I _{DDC1}		2	20	μΑ	Outputs unloaded, Input signals static, not loaded
2	Dynamic Supply Current: Total all functions enabled	I _{DDFT}		6	10	mA	See Note 1.

Note 1: Power delivered to the load is in addition to the bias current requirements.

$\textbf{DC Electrical Characteristics}^{\dagger} \text{ - Voltages are with respect to ground (V}_{SS}) \text{ unless otherwise stated.}$

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions
1	Input HIGH Voltage CMOS inputs	V _{IHC}	0.7*Vdd			V	
2	Input LOW Voltage CMOS inputs	V _{ILC}			0.3*Vdd	V	
3	VBias Voltage Output	V _{Bias}		V _{DD} /2		>	Max. Load = $10 \text{ k}\Omega$
4	V _{Ref} Output Voltage	V_{Ref}		V _{DD} /2-1.1		>	No load
5	Input Leakage Current	I _{IZ}		0.1	10	μΑ	$V_{IN}=V_{DD}$ to V_{SS}
6	Positive Going Threshold Voltage (PWRST only)	V _{T+}	2.2			٧	Vdd=3V
	Negative Going Threshold Voltage (PWRST only)	V _{T-}			0.7	V	
	Hysteresis			0.65		V	
7	Output HIGH Current	Іон	1.0			mA	V _{OH} = 0.9*V _{DD} See Note 1
8	Output LOW Current	I _{OL}	2.5			mA	V _{OL} = 0.1*V _{DD} See Note 1
9	Output Leakage Current	l _{OZ}		0.01	10	μΑ	$V_{OUT} = V_{DD}$ and V_{SS}
10	Output Capacitance	Co		15		pF	
11	Input Capacitance	C _i		10		pF	

[†] DC Electrical Characteristics are over recommended temperature range & recommended power supply voltages.

Clockin Tolerance Characteristics[†]

	Characteristics	Min.	Typ. [‡]	Max.	Units.	Test Conditions
1	CLOCKin Frequency (Asynchronous Mode)	4095.6	4096	4096.4	kHz	(i.e., 100 ppm)

[†] AC Electrical Characteristics are over recommended temperature range & recommended power supply voltages.

[‡] Typical figures are at 25 °C and are for design aid only: not guaranteed and not subject to production testing. * Note 1 - Magnitude measurement, ignore signs.

[‡] Typical figures are at 25 °C and are for design aid only: not guaranteed and not subject to production testing.

AC Characteristics † for A/D (Transmit) Path - 0 dBm0 = A_{Lo3.17} - 3.17 dB = 1.027 V_{rms} for μ -Law and 0 dBm0 = A_{Lo3.14} - 3.14 dB = 1.06 7V_{rms} for A-Law, at the Codec. (V_{Ref}=0.4 volts and V_{Bias}=1.5 volts.)

	Characteristics	Sym.	Min.	Typ.‡	Max.	Units	Test Conditions
1	Analog input equivalent to overload decision	A _{Li3.17} A _{Li3.14}		4.246 4.4		Vp-p Vp-p	μ-Law A-Law Both at Codec
2	Absolute half-channel gain $\label{eq:mass_def} \textbf{M} \pm \textbf{to Dout}$	G _{AX1}	5.4	6.0	6.6	dB	Transmit filter gain=0dB setting. @1020Hz
3	Gain tracking vs. input level ITU-T G.714 Method 2	G _{TX}	-0.3 -0.6 -1.6		0.3 0.6 1.6	dB dB dB	3 to -40 dBm0 -40 to -50 dBm0 -50 to -55 dBm0
4	Signal to total Distortion vs. input level. ITU-T G.714 Method 2	D_{QX}	35 29 24			dB dB dB	0 to -30 dBm0 -40 dBm0 -45 dBm0
5	Transmit Idle Channel Noise	N _{CX} N _{PX}		13 -70.5	16 -69	dBrnC0 dBm0p	μ-Law A-Law
6	Gain relative to gain at 1020 Hz <50 Hz 60 Hz 200 Hz 300 - 3000 Hz 3000-3300 Hz 3300 Hz 3400 Hz 4000 Hz 4600 Hz >4600 Hz	G _{RX}	-0.25 -0.9 -0.9 -1.2	-45 -0.2 -0.6 -23 -41	-25 -30 0.0 0.25 0.25 0.25 0.25 -12.5 -25	dB dB dB dB dB dB dB dB	
7	Absolute Delay	D _{AX}		360		μS	at frequency of minimum delay
8	Group Delay relative to D _{AX}	D _{DX}		750 380 130 750		μs μs μs μs	500-600 Hz 600 - 1000 Hz 1000 - 2600 Hz 2600 - 2800 Hz
9	Power Supply Rejection f=1020 Hz	PSSR	30	50		dB	±100mV peak signal on V _{DD} μ-law

[†] AC Electrical Characteristics are over recommended temperature range & recommended power supply voltages.

[‡] Typical figures are at 25 °C and are for design aid only: not guaranteed and not subject to production testing.

AC Characteristics † for D/A (Receive) Path - 0 dBm0 = A_{Lo3.17} - 3.17 dB = 1.027 V_{rms} for μ -Law and 0 dBm0 = A_{Lo3.14} - 3.14 dB = 1.067 V_{rms} for A-Law, at the Codec. (V_{Ref}=0.4 volts and V_{Bias}=1.5 volts.)

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions
1	Analog output at the Codec full scale	A _{Lo3.17} A _{Lo3.14}		4.183 4.331		Vp-p Vp-p	μ-Law A-Law
1	Analog output at the CODEC full scale.	A _{Lo3.17} A _{Lo3.14}		4.183 4.331		$V_{p-p} \ V_{p-p}$	μ-Law A-Law
2	Absolute half-channel gain. Din to HSPKR±	G _{AR1}	-0.6	0	0.6	dB	@1020Hz
3	Gain tracking vs. input level ITU-T G.714 Method 2	G _{TR}	-0.3 -0.6 -1.6		0.3 0.6 1.6	dB dB dB	3 to -40 dBm0 -40 to -50 dBm0 -50 to -55 dBm0
4	Signal to total distortion vs. input level. ITU-T G.714 Method 2	G _{QR}	35 29 24			dB dB dB	0 to -30 dBm0 -40 dBm0 -45 dBm0
5	Receive Idle Channel Noise	N _{CR} N _{PR}		11.5 -80	14 -77	dBrnC0 dBm0p	μ-Law A-Law
6	Gain relative to gain at 1020 Hz 200 Hz 300 - 3000 Hz 3000 - 3300 Hz 3300 Hz 3400 Hz 4000 Hz 4600 Hz >4600 Hz	G _{RR}	-0.25 -0.90 -0.9 -0.9	-0.1 -0.5 -23 -41	0.25 0.25 0.25 0.25 0.25 -12.5 -25 -25	dB dB dB dB dB dB dB	
7	Absolute Delay	D _{AR}		240		μs	at frequency of min. delay
8	Group Delay relative to D _{AR}	D _{DR}		750 380 130 750		μs μs μs μs	500-600 Hz 600 - 1000 Hz 1000 - 2600 Hz 2600 - 2800 Hz
9	Crosstalk D/A to A/D A/D to D/A	CT _{RT} CT _{TR}		-90 -90	-74 -80	dB dB	G.714.16 ITU-T

[†] AC Electrical Characteristics are over recommended temperature range & recommended power supply voltages.

Electrical Characteristics[†] for Analog Outputs

	Characteristics	Sym.	Min.	Typ.‡	Max.	Units	Test Conditions
1	Output load impedance	E _{ZL}	20k			ohms	across AOUT±
2	Allowable output capacitive load	E _{CL}		20		pF	each pin: AOUT+, AOUT-

[†] Electrical Characteristics are over recommended temperature range & recommended power supply voltages.

[‡] Typical figures are at 25 °C and are for design aid only: not guaranteed and not subject to production testing.

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Electrical Characteristics[†] for Analog Inputs

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions
1	Maximum input voltage without overloading Codec across AOUT+/AOUT-	V _{IOLH}		2.128 2.20		Vp-p Vp-p	$A/\overline{\mu} = 0$ $A/\mu = 1$
2	Input Impedance	Z _I	50			kΩ	Ain+/Ain- to V _{SS}

[†] Electrical Characteristics are over recommended temperature range & recommended power supply voltages.

AC Electrical Characteristics[†] - SSI BUS Synchronous Timing (see Figure 5)

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions
1	BCL Clock Period	t _{BCL}	244		1953	ns	BCL=4096 kHz to 512 kHz
2	BCL Pulse Width High	t _{BCLH}	115	122		ns	BCL=4096 kHz
3	BCL Pulse Width Low	t _{BCLL}		122		ns	BCL=4096 kHz
4	BCL Rise/Fall Time	t _R /t _F		20		ns	Note 1
5	Strobe Pulse Width	t _{ENW}		8 x t _{BCL}		ns	Note 1
6	Strobe setup time before BCL falling	t _{SSS}	70		t _{BCL} -80	ns	
7	Strobe hold time after BCL falling	t _{SSH}	80		t _{BCL} -80	ns	
8	Dout High Impedance to Active Low from Strobe rising	t _{DOZL}			55	ns	C _L =50 pF, R _L =1K
9	Dout High Impedance to Active High from Strobe rising	t _{DOZH}			55	ns	C _L =50 pF, R _L =1K
10	Dout Active Low to High Impedance from Strobe falling	t _{DOLZ}			90	ns	C _L =50 pF, R _L =1K
11	Dout Active High to High Impedance from Strobe falling	t _{DOHZ}			90	ns	C _L =50 pF, R _L =1K
12	Dout Delay (high and low) from BCL rising	t _{DD}			80	ns	C _L =50 pF, R _L =1K
13	Din Setup time before BCL falling	t _{DIS}	10			ns	
14	Din Hold Time from BCL falling	t _{DIH}	50			ns	

[†] Timing is over recommended temperature range & recommended power supply voltages.

NOTE 1: Not production tested, guaranteed by design.

[‡] Typical figures are at 25 °C and are for design aid only: not guaranteed and not subject to production testing.

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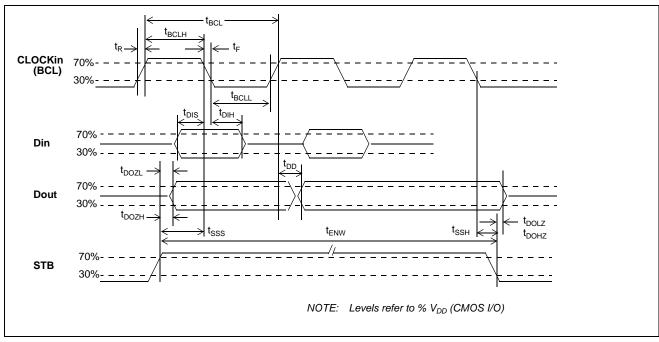


Figure 5 - SSI Synchronous Timing Diagram

AC Electrical Characteristics[†] - SSI BUS Asynchronous Timing (note 1) (see Figure 6)

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions
1	Bit Cell Period	T _{DATA}		7812 3906		ns ns	BCL=128 kHz BCL=256 kHz
2	Frame Jitter	T _j			600	ns	
3	Bit 1 Dout Delay from STB going high	t _{dda1}			T _j +600	ns	C _L =50 pF, R _L =1K
4	Bit 2 Dout Delay from STB going high	t _{dda2}	600+ T _{DATA} -T _j	600+ T _{DATA}	600 + T _{DATA} +T _j	ns	C _L =50 pF, R _L =1K
5	Bit n Dout Delay from STB going high	t _{ddan}	600 + (n-1) x T _{DATA} -T _j	600 + (n-1) x T _{DATA}	600 + (n-1) x T _{DATA} +T _j	ns	C _L =50 pF, R _L =1K n=3 to 8
6	Bit 1 Data Boundary	T _{DATA1}	T_{DATA} - T_{j}		$T_{DATA}+T_{j}$	ns	
7	Din Bit n Data Setup time from STB rising	t _{SU}	$T_{DATA}\2$ +500ns- T_{j} +(n-1) x T_{DATA}			ns	n=1-8
8	Din Data Hold time from STB rising	t _{ho}	$T_{DATA}\2$ +500ns+ T_{j} +(n-1) x T_{DATA}			ns	

[†] Timing is over recommended temperature range & recommended power supply voltages.

[‡] Typical figures are at 25°C and are for design aid only: not guaranteed and not subject to production testing. NOTE 1:Not production tested, guaranteed by design.

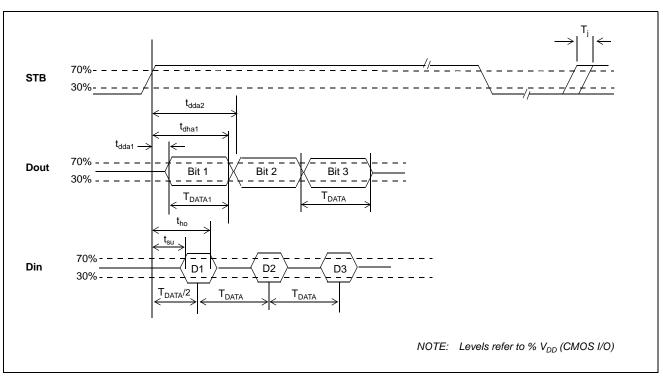
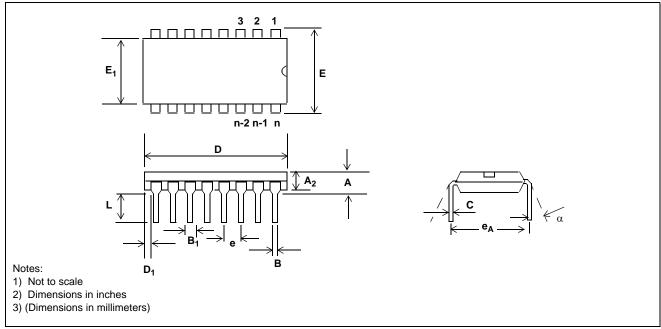


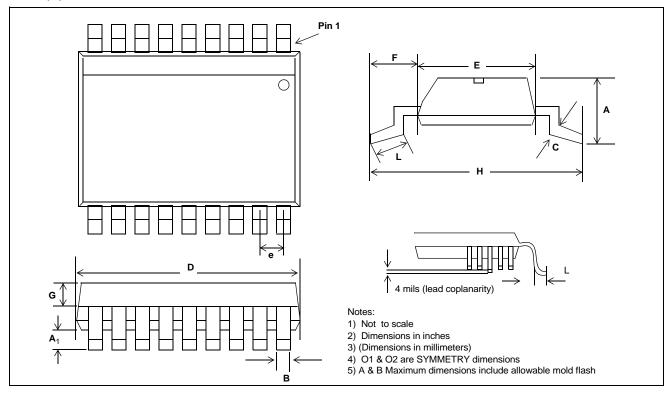
Figure 6 - SSI Asynchronous Timing Diagram



Plastic Dual-In-Line Packages (PDIP) - E Suffix

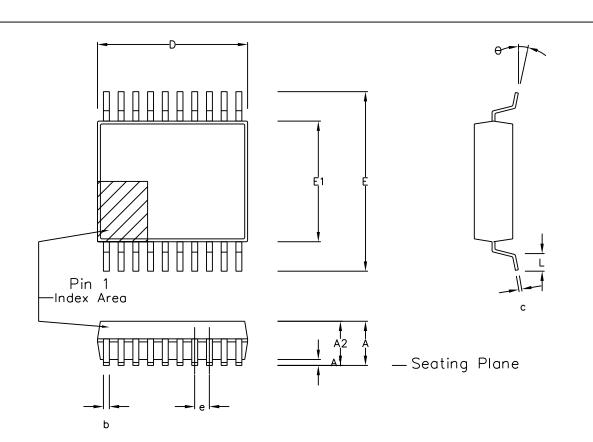
	8-1	Pin	16-	Pin	18-	Pin	20-	Pin
DIM	Pla	stic	Pla	stic	Pla	stic	Pla	stic
	Min	Max	Min	Max	Min	Max	Min	Max
Α		0.210 (5.33)		0.210 (5.33)		0.210 (5.33)		0.210 (5.33)
A ₂	0.115 (2.93)	0.195 (4.95)	0.115 (2.93)	0.195 (4.95)	0.115 (2.93)	0.195 (4.95)	0.115 (2.93)	0.195 (4.95)
В	0.014 (0.356)	0.022 (0.558)	0.014 (0.356)	0.022 (0.558)	0.014 (0.356)	0.022 (0.558)	0.014 (0.356)	0.022 (0.558)
B ₁	0.045 (1.15)	0.070 (1.77)	0.045 (1.15)	0.070 (1.77)	0.045 (1.15)	0.070 (1.77)	0.045 (1.15)	0.070 (1.77)
С	0.008 (0.204)	0.015 (0.381)	0.008 (0.204)	0.015 (0.381)	0.008 (0.204)	0.015 (0.381)	0.008 (0.204)	0.015 (0.381)
D	0.348 (8.84)	0.430 (10.92)	0.745 (18.93)	0.840 (21.33)	0.845 (21.47)	0.925 (23.49)	0.925 (23.49)	1.060 (26.9)
D ₁	0.005 (0.13)		0.005 (0.13)		0.005 (0.13)		0.005 (0.13)	
Е	0.290 (7.37)	0.330 (8.38)	0.290 (7.37)	0.330 (8.38)	0.290 (7.37)	0.330 (8.38)	0.290 (7.37)	0.330 (8.38)
E ₁	0.240 (6.10)	0.280 (7.11)	0.240 (6.10)	0.280 (7.11)	0.240 (6.10)	0.280 (7.11)	0.240 (6.10)	0.280 (7.11)
е	0.100 BS	SC (2.54)	0.100 BS	SC (2.54)	0.100 BS	SC (2.54)	0.100 BS	SC (2.54)
e ₁								
e _A	0.300 BS	SC (7.62)	0.300 BS	SC (7.62)	0.300 BS	SC (7.62)	0.300 BS	SC (7.62)
L	0.115 (2.93)	0.160 (4.06)	0.115 (2.93)	0.160 (4.06)	0.115 (2.93)	0.160 (4.06)	0.115 (2.93)	0.160 (4.06)
S								
α		15°		15°		15°		15°

NOTE: () Millimeters



DIM	16-	Pin	18-	Pin	20-	Pin	24-	Pin	28-	Pin
DIN	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
Α	0.093	0.104	0.093	0.104	0.093	0.104	0.093	0.104	0.093	0.104
	(2.35)	(2.65)	(2.35)	(2.65)	(2.35)	(2.65)	(2.35)	(2.65)	(2.35)	(2.65)
A ₁	0.004	0.012	0.004	0.012	0.004	0.012	0.004	0.012	0.004	0.012
	(0.10)	(0.30)	(0.10)	(0.30)	(0.10)	(0.30)	(0.10)	(0.30)	(0.10)	(0.30)
В	0.014	0.019	0.014	0.019	0.014	0.019	0.014	0.019	0.014	0.019
	(0.351)	(0.488)	(0.351)	(0.488)	(0.351)	(0.488)	(0.351)	(0.488)	(0.351)	(0.488)
С	0.009	0.013	0.009	0.013	0.009	0.013	0.009	0.013	0.009	0.013
	(0.231)	(0.318)	(0.231)	(0.318)	(0.231)	(0.318)	(0.231)	(0.318)	(0.231)	(0.318)
D	0.398	0.413	0.447	0.469	0.496	0.518	0.598	0.614	0.697	0.712
	(10.1)	(10.5)	(11.35)	(11.90)	(12.60)	(13.00)	(15.2)	(15.6)	(17.7)	(18.1)
E	0.291	0.305	0.291	0.305	0.291	0.305	0.291	0.305	0.291	0.305
	(7.40)	(7.75)	(7.40)	(7.75)	(7.40)	(7.75)	(7.40)	(7.75)	(7.40)	(7.75)
е		BSC BSC)	0.050 BSC (1.27 BSC)							
F	0.044	0.064	0.044	0.064	0.044	0.064	0.044	0.064	0.044	0.064
	(1.125)	(1.625)	(1.125)	(1.625)	(1.125)	(1.625)	(1.125)	(1.625)	(1.125)	(1.625)
G	0.040	0.050	0.040	0.050	0.040	0.050	0.040	0.050	0.040	0.050
	(1.016)	(1.270)	(1.016)	(1.270)	(1.016)	(1.270)	(1.016)	(1.270)	(1.016)	(1.270)
Н	0.394	0.419	0.394	0.419	0.394	0.419	0.394	0.419	0.394	0.419
	(10.00)	(10.65)	(10.00)	(10.65)	(10.00)	(10.65)	(10.00)	(10.65)	(10.00)	(10.65)
L	0.016	0.050	0.016	0.050	0.016	0.050	0.016	0.050	0.016	0.050
	(0.40)	(1.27)	(0.40)	(1.27)	(0.40)	(1.27)	(0.40)	(1.27)	(0.40)	(1.27)

Lead SOIC Package - S Suffix



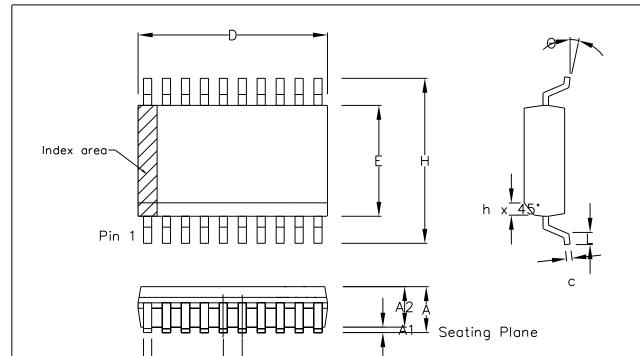
		ol Dimer			Alterr	n. Dimer			
Symbol	.in	millimeti	res		in inches				
	MIN	Nominal	MAX		MIN	Nominal	MAX		
Α	1.70		2.00		0.067		0.079		
A1	0.05		0.20		0.002		0.008		
A2	1.65		1.85		0.065		0.073		
D	6.90		7.50		0.272		0.295		
E	7.40		8.20		0.291		0.323		
E1	5.00		5.60		0.197		0.220		
L	0.55		0.95		0.022		0.037		
е	0.0	65 BS	SC.		0.026 BSC.				
р	0.22		0.38		0.009		0.015		
С	0.09		0.25		0.004		0.010		
Φ	0°		8°		0.		8.		
	Pin features								
N	20								
Con	Conforms to JEDEC MO-150 AE Iss. B								
	CONTRACTOR TO CEDEC INTO TOO ME 100. D								

This drawing supersedes: -418/ED/51481/002 (Swindon/Plymouth)

Notes:

- 1. A visual index feature, e.g. a dot, must be located within the cross—hatched area.
- 2. Controlling dimension are in millimeters.
- 3. Dimensions D and E1 do not include mould flash or protusion. Mould flash or protusion shall not exceed
- 0.20 mm per side. D and E1 are maximum plastic body size dimensions including mould mismatch.
 4. Dimension b does not include dambar protusion/intrusion. Allowable dambar protusion shall be 0.13 mm total in excess of b dimension. Dambar intrusion shall not reduce dimension b by more than 0.07 mm.

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ISSUE	1	2	3		Previous package codes	Package Outline for 20 lead
ACN	201933	205234	212477	ZARLINK SEMICONDUCTOR	NP / N	SSOP (5.3mm Body Width)
DATE	27Feb97	25Sep98	3Apr02	Valline Grand Grand		
APPRD.						GPD00294



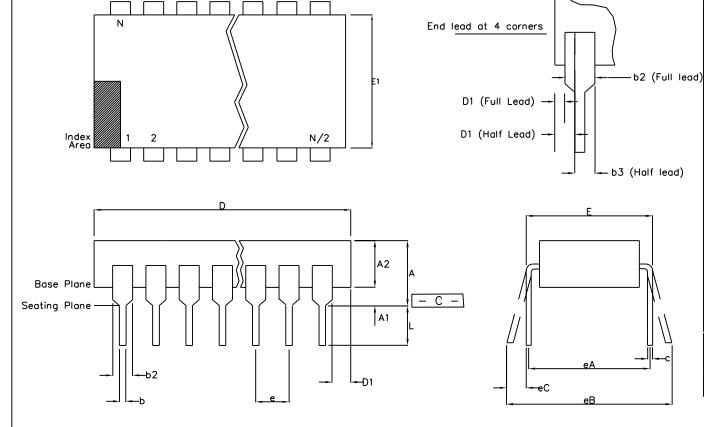
	Contro	ol Dime	nsions		Altern	. Dimer	nsions		
Symbol	in	<u>millimet</u>	res		in inches				
		Nominal				Nominal			
Α	2.35		2.65		0.093		0.104		
A1	0.10		0.30		0.004		0.012		
Α2	2.25		2.35		0.089		0.092		
D	12.60		13.00		0.496		0.512		
Η	10.00		10.65		0.394		0.419		
Ε	7.40		7.60		0.291		0.299		
L	0.40		1.27		0.016		0.050		
е	1.2	27 BS	C.		0.050 BSC.				
b	0.33		0.51		0.013		0.020		
С	0.23		0.32		0.009		0.013		
θ	0.		8		0,		8°		
h	0.25		0.75		0.010		0.029		
	Pin features								
N	20								
Cor	nforms	s to .	JEDEC	MS	-013	AC Iss	s. C		

Notes:

- 1. The chamfer on the body is optional. If it not present, a visual index feature, e.g. a dot, must be located within the cross—hatched area.
- 2. Controlling dimension are in millimeters.

- 3. Dimension D do not include mould flash, protrusion or gate burrs. These shall not exceed 0.006" per side.
 4. Dimension E1 do not include inter—lead flash or protrusion. These shall not exceed 0.010" per side.
 5. Dimension b does not include dambar protrusion/intrusion. Allowable dambar protrusion shall be 0.004" total in excess of b dimension.

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ISSUE	1	2	3			Previous package codes	Package Outline for
ACN	6746	201941	213098		ZARLINK SEMICONDUCTOR	MP/S	20 lead SOIC (0.300" Body Width)
DATE	7Apr95	27Feb97	15Jul02		32mres no octor	, , ,	(e.eee Beey mann)
APPRD.							GPD00015



	Min	Max	Min	Max					
	mm	mm	<u>Inches</u>	<u>Inches</u>					
Α		5.33		0.210					
A1	0.38		0.015						
A2	2.92	4.95	0.115	0.195					
b	0.36	0.56	0.014	0.022					
b2	1.14	1.78	0.045	0.070					
b3	n/a	n/a	n/a	n/a					
С	0.20	0.36	0.008	0.014					
D	24.89	26.92	0.980	1.060					
D1	0.13		0.005						
Е	7.62	8.26	0.300	0.325					
E1	6.10	7.11	0.240	0.280					
е	2.54	BSC	0.100	BSC					
eА	7.62	BSC	0.300) BSC					
eВ		10.92		0.430					
еC	0.00	1.52	0.000	0.060					
L	2.92	3.81	0.115	0.150					
N	2	0	20						
Conforr	Conforms to Jedec MS-001AD Issue D								

Notes:

4. Controlling dimensions are Inches. Millimeter conversions are not necessarily exact.

5. N is the maximum of terminal positions.

This drawing supersedes: -UK drawing # 418/ED/39502/005

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ISSUE	1	2				Previous package codes	Package Outline for 20 lead PDIP
ACN	202562	213107			ZARLINK SEMICONDUCTOR	DP / E	
DATE	9Jun97	15Jul02			3EMICONDOCTOR	/	00000747
APPRD.							GPD00347



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